Customer Service Note

Introduction

Micron follows specific packaging procedures to help ensure safe transport of our products. This customer service note describes a wide range of topics concerning the packaging and shipping of Micron® semiconductors, modules and SSDs, including:

- Packaging Procedures
- Air Allowance in Moisture-Barrier and Static-Shielding Bags
- Humidity Indicator Cards
- Pin 1 Orientation for Tray and Tape-and-Reel Packaging
- Carrier Tape Design Details
- Component Packaging Materials Composition

Packaging Procedures

For shipping, Micron packages its semiconductor, module, and SSD products in product-specific trays and tape-and-reel carriers.¹ Each method may include a desiccant pack, HIC, moisture-barrier or static-shielding bag, internal padding, boxes, and packing labels. The following figures outline the packing sequence for each packaging method.

Notes: 1. For actual tray and box quantities, refer to CSN-04, “Shipping Quantities.”
Figure 1: Tray Packaging

Final tray packages may be placed in a master shipping container in configurations of 1, 2, 3, 4, 6, 9, and 12.

Figure 2: ESD Tape Example
Final tape-and-reel packages may be placed in a master shipping container in configurations of 1, 2, 3, 4, 6, 8, 10, and 20.
The security tape shown in Figure 5 is an example of the tape Micron uses to seal all open ends of outer shipping containers. A single box may be shipped without a shipping container, but the security tape will still be applied.

**Figure 4: Module Packaging**

- Any partially filled tray will be placed on top.
- ESD tape
- Opening side
- Non-opening side
- Spec label (optional)
- Box label
- Master container
- Empty space in the container may be padded with fillers.
- Security tape
- Completed master container
- The actual size and shape of the container, and the position of tape may vary depending on product and quantity.

**Figure 5: Shipping Container Security Tape Example**

*VOID IF CUT OR TAMPERED*
Figure 6: 1.8-Inch SSD Packaging

1. ESD-protected SSD is then inserted into the foam cell divider slots.
2. Foam insert is placed on top of the SSD.
3. ESD tape is applied to secure the packaging.
4. Box label and non-opening side are marked.
5. Inner box is placed inside the outer box.
6. Static-shielded bag is used for protection.
Figure 7: 2.5-Inch SSD Packaging

- SSDs are placed directly into the tray.
- Loaded trays are stacked.
- An empty tray is used as the lid.

Opening side
- ESD tape
- Spec label (optional)
- Box label

Non-opening side

Shipper
Figure 8: mSATA SSD Packaging
Figure 9: M.2 SSD Packaging

- M.2 SSD shipping tray lid
- Shipping tray
- Completed shipping tray with lid in place
- Shipping box, holds two trays
- ESD tape
- Box label
- Spec label (optional)
Figure 10: M.2 SSD Flat-Tray Packaging

- M.2 SSD flat shipping tray used as lid
- Stacked shipping trays
- Completed shipping trays with lid in place
- Shipping box
- ESD tape
- Box label
- Spec label (optional)
Figure 11: Embedded USB (eUSB) Packaging

- eUSB shipping tray lid
- eUSB shipping tray
- Full shipping tray
- Shipping box, holds two tray
- ESD tape
- Box label
- Spec label (optional)
Figure 12: MicroSD Packaging

MicroSD shipping tray used as lid

Completed trays in pink bubble wrap

Edged corner

Inner shipping box (Empty space filled with pink bubble wrap)

Completed shipping trays Maximum 15 full trays + 1 cover tray Minimum 4 full trays + 1 cover tray

Completed shipping trays with strapping

Box label

Opening side

ESD tape
Air Allowance in Moisture-Barrier and Static-Shielding Bags

Moisture-barrier and static-shielding bags are packed with some allowance for air to facilitate maximum moisture absorption. As such, some variation in the amount of air within the bags is to be expected. However, if questions arise regarding the moisture content of the bagged product or if the enclosed humidity indicator card indicates any abnormality, please refer to the section Humidity Indicator Cards or to Micron Technical Note TN-00-01, “Moisture Sensitivity of Plastic Packages.”

There is no shelf life for module-level products (for example, DIMMs and SSDs). The memory components are humidity sensitive, which can affect their performance and reliability during mounting. When mounted, these components are no longer moisture sensitive.

Humidity Indicator Cards

Micron provides a humidity indicator card (HIC) and desiccant pack with all non-level 1 surface-mount products. The HIC provides an indication of the relative humidity (RH) level of the packaged contents. Review the Packaging Procedures section for the general placement of a standard HIC and desiccant for each of Micron’s packaging methods.

Micron is in the process of changing the HICs we use to comply with both the IPC/JEDEC J-STD-033 standard and all REACH regulations (cobalt dichloride free). During the transition, customers may receive either format. For this reason, Figures 14–18 show both formats.
Evaluating the RH Levels of Dry Pack Shipments

The RH level within the moisture-barrier bag can be determined by inspecting the HIC. Micron recommends inspecting the HIC under the following conditions:

- The HIC should be read immediately after opening the moisture-barrier bag.
- For accuracy, the HIC should be read at 23°C ±5°C.

If the devices are to be repackaged in a moisture-barrier bag, replace both the desiccant and the HIC.

The HIC’s color dots should be evaluated using the following guidelines.

5% RH

If the 5%, 10%, and 60% dots are blue (see Figure 5), the devices are adequately dry, and no baking is required.

Figure 14: 5% RH

![Humidity Indicator Cards](image)
If the 5% dot is pink and the 10% or 60% dots are blue (see Figure 15), the devices are adequately dry, and no baking is required.

Figure 15: <10% RH

**HUMIDITY INDICATOR**
Complies with IPC/JEDEC J-STD-033B

<table>
<thead>
<tr>
<th>LEVEL</th>
<th>PARTS</th>
<th>%</th>
</tr>
</thead>
<tbody>
<tr>
<td>2 PARTS</td>
<td>60%</td>
<td></td>
</tr>
<tr>
<td>2A-5A PARTS</td>
<td>10%</td>
<td></td>
</tr>
<tr>
<td>5%</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Initial use: Do not put this card into a bag if 60% is pink.

**COBALT DICHLORIDE FREE**
Complies with IPC/JEDEC J-STD-033 and all REACH regulations

<table>
<thead>
<tr>
<th>LEVEL</th>
<th>PARTS</th>
<th>%</th>
</tr>
</thead>
<tbody>
<tr>
<td>2 PARTS</td>
<td>60%</td>
<td></td>
</tr>
<tr>
<td>2A-5A PARTS</td>
<td>10%</td>
<td></td>
</tr>
<tr>
<td>5%</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Initial use: Do not put this card into a bag if 60% is pink.

10% RH

If the 5% dot is pink, 10% dot is lavender, and the 60% dot is blue (see Figure 16), the devices are adequately dry, and no baking is required.

Figure 16: 10% RH

**HUMIDITY INDICATOR**
Complies with IPC/JEDEC J-STD-033B

<table>
<thead>
<tr>
<th>LEVEL</th>
<th>PARTS</th>
<th>%</th>
</tr>
</thead>
<tbody>
<tr>
<td>2 PARTS</td>
<td>60%</td>
<td></td>
</tr>
<tr>
<td>2A-5A PARTS</td>
<td>10%</td>
<td></td>
</tr>
<tr>
<td>5%</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Initial use: Do not put this card into a bag if 60% is pink.

**COBALT DICHLORIDE FREE**
Complies with IPC/JEDEC J-STD-033B

<table>
<thead>
<tr>
<th>LEVEL</th>
<th>PARTS</th>
<th>%</th>
</tr>
</thead>
<tbody>
<tr>
<td>2 PARTS</td>
<td>60%</td>
<td></td>
</tr>
<tr>
<td>2A-5A PARTS</td>
<td>10%</td>
<td></td>
</tr>
<tr>
<td>5%</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Initial use: Do not put this card into a bag if 60% is pink.
>10% RH

If the 5% and 10% dots are pink and the 60% dot is blue (see Figure 17), the devices have been exposed to an excessive level of moisture, and they must be dried per IPC/JEDEC J-STD-033B, Clause 4. Upon completion of the recommended bake, the devices can be repacked in a moisture-barrier bag with a new desiccant and a new HIC.

Figure 17: >10% RH

If the 5%, 10%, and 60% dots are pink (see Figure 18), the devices have been exposed to an excessive level of moisture, and they must be dried per IPC/JEDEC J-STD-033B, Clause 4. Upon completion of the recommended bake, the devices can be repacked in a moisture-barrier bag with a new desiccant and a new HIC.

Figure 18: 60% RH
Pin 1 Orientation for Tray and Tape-and-Reel Packaging

Pin 1 refers to the location of the first lead or ball inside a semiconductor device and is used to determine how a part is attached to a circuit board. In a corner on the topside of each Micron device, pin 1 is indicated by an indentation, either a molded dot or a molded “MT,” or it is indicated by a mark, specifically, a laser-etched dot or a laser-etched “MT.” This section explains the locations of the pin 1 indicators on Micron’s devices shipped in tray and tape-and-reel packaging.

Location of Pin 1 in Tray Packaging

Micron uses several different types of trays with varying colors for shipping products. However, each tray has a single beveled corner that indicates the direction pin 1 faces on each device. Depending on the package type and the design ID of the part, the pin 1 indicator will be located in one of the two corners of the device edge closest to the beveled corner of the tray. For square BGA packages, pin 1 is always positioned in the A location. An example is shown in Figure 19.

Figure 19: Pin 1 Direction on Trays

1. For square BGA packages, pin 1 is always positioned in the A location.

Location of Pin 1 in Tape-and-Reel Packaging

Depending on their package type and design ID, devices shipped in tape-and-reel carriers are positioned so that the pin 1 indicator on each device is located in one of the two corners that faces the edge of the carrier tape with the round sprocket holes. For square BGA packages, pin 1 is always positioned in the A location. Figure 20 on page 17 illustrates the position of the pin 1 indicators on Micron’s tape-and-reel carriers.
Carrier Tape Design Details

Micron supports the Electronic Industries Association’s (EIA) standardization of tape-and-reel specifications, number 481-D. Specifications for our tape-and-reel offerings are detailed in the following figures and tables.

1. For square BGA packages, pin 1 is always positioned in the A location.

Notes: 1. The leader and trailer lengths on Micron’s tape-and-reel carriers are >400mm and >160mm, respectively.
Figure 22: Bending Radius

Notes: 1. Tape and components shall pass around radius “R” without damage.

Figure 23: Camber (top view)

Notes: 1. Allowable camber to be 1mm/250mm.
Figure 24: Embossed Carrier Dimensions (16mm and 24mm tape)

Table 1: 16mm and 24mm Embossed Tape Dimensions

<table>
<thead>
<tr>
<th>Tape Size</th>
<th>ØD</th>
<th>E</th>
<th>P0</th>
<th>t (MAX)</th>
<th>A0, B0, K0</th>
<th>B1 (MAX)</th>
<th>ØD1 (MIN)</th>
</tr>
</thead>
<tbody>
<tr>
<td>16mm</td>
<td>1.5 +0.10/-0.00</td>
<td>1.75 ±0.10</td>
<td>4.0 ±0.10</td>
<td>0.6</td>
<td>Note 2</td>
<td>12.1 (0.476)</td>
<td>1.5</td>
</tr>
<tr>
<td>24mm</td>
<td>20.1 (0.791)</td>
<td>24.3 (0.957)</td>
<td>4.0 ±0.10 to 20.0 ±0.10</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Notes: 1. All dimensions in millimeters (inches).
2. The cavity defined by A0, B0, and K0 shall surround the component with sufficient clearance that:
   2a. The component does not protrude above the top surface of the carrier tape.
   2b. After the top cover tape has been removed, the component can be removed from the cavity in a vertical direction without mechanical restriction.
   2c. Rotation of the component is limited to 10 degrees maximum for 16mm and 24mm tapes.
   2d. Lateral movement of the component is restricted to 1.0mm MAX for 16mm- and 24mm-wide tapes. See Figure 27 on page 21.

1. Tape and components shall pass around radius “R” without damage. Refer to Figure 22 on page 18.
Figure 25: Embossed Carrier Dimensions (32mm and 44mm tape only)

B1 is for machine reference only, including draft and radii concentric around B0.

Center lines of cavity

OD – Round sprocket holes this side

P0 10 pitches cumulative tolerance on tape ±0.2mm (±0.008in.)

Notes:

1. The cavity defined by A0, B0, and K0 shall surround the component with sufficient clearance that:
   1a. The component does not protrude above the top surface of the carrier tape.
   1b. After the top cover tape has been removed, the component can be removed from the cavity in a vertical direction without mechanical restriction.
   1c. Rotation of the component is limited to 10 degrees maximum for 32mm and 44mm tapes.
   1d. Lateral movement of the component is restricted to 1.0mm MAX for 32mm- and 44mm-wide tapes. See Figure 27 on page 21.

Figure 26: Detail of Elongated Hole
Figure 27: Maximum Lateral Movement for Punched and Embossed Carrier

![Diagram showing maximum lateral movement for punched and embossed carrier tapes]

Table 2: 32mm and 44mm Embossed Tape

<table>
<thead>
<tr>
<th>Tape Size</th>
<th>ØD (MIN)</th>
<th>ØD1 (MIN)</th>
<th>E</th>
<th>K (MAX)</th>
<th>P0</th>
<th>t (MAX)</th>
<th>A0, B0, K0</th>
<th>B1 (MAX)</th>
</tr>
</thead>
<tbody>
<tr>
<td>32mm</td>
<td>1.5 +0.10/-0.00 (0.059) +0.004/-0.000</td>
<td>2.0 (0.079)</td>
<td>1.75 ±0.10 (0.069 ±0.004)</td>
<td>12.0 (0.472)</td>
<td>4.0 ±0.10 (0.157 ±0.004)</td>
<td>0.6 (0.024)</td>
<td>Note 2</td>
<td>23.0 (0.906)</td>
</tr>
<tr>
<td>44mm</td>
<td>16.0 (0.630)</td>
<td>2.0 ±0.10 (0.079 ±0.004)</td>
<td>12.0 (0.472)</td>
<td>4.0 ±0.10 (0.157 ±0.004)</td>
<td>0.6 (0.024)</td>
<td>Note 2</td>
<td>35.0 (1.378)</td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Tape Size</th>
<th>F</th>
<th>P2</th>
<th>S</th>
<th>W</th>
<th>R (MIN)</th>
<th>P (4.0 increments)</th>
</tr>
</thead>
<tbody>
<tr>
<td>32mm</td>
<td>14.2 ±0.10 (0.559 ±0.004)</td>
<td>2.0 ±0.10 (0.079 ±0.004)</td>
<td>28.4 ±0.10 (1.118 ±0.004)</td>
<td>32.0 ±0.30 (1.26 ±0.012)</td>
<td>50 (1.973) See Note 3</td>
<td>4.0 ±0.10 to 32.0 ±0.10</td>
</tr>
<tr>
<td>44mm</td>
<td>20.2 ±0.15 (0.795 ±0.006)</td>
<td>2.0 ±0.15 (0.079 ±0.006)</td>
<td>40.4 ±0.10 (1.591 ±0.004)</td>
<td>44.0 ±0.30 (1.732 ±0.012)</td>
<td>See Note 3</td>
<td>4.0 ±0.10 to 44.0 ±0.10</td>
</tr>
</tbody>
</table>

Notes:
1. All dimensions in millimeters (inches).
2. The cavity defined by A0, B0, and K0 shall surround the component with sufficient clearance that:
   2a. The component does not protrude above the top surface of the carrier tape.
   2b. After the top cover tape has been removed, the component can be removed from the cavity in a vertical direction without mechanical restriction.
   2c. Rotation of the component is limited to 10 degrees maximum for 32mm and 44mm tapes.
   2d. Lateral movement of the component is restricted to 1.0mm MAX for 32mm- and 44mm-wide tapes. See Figure 27.
3. Tape and components shall pass around radius “R” without damage. See Figure 22 on page 18.
Component Packaging Materials Composition

To package its semiconductor memory for delivery, Micron uses two basic methods: tray and tape-and-reel. Where possible, Micron incorporates recyclable materials both in the internal packing materials and in the external coverings. Table 3 on page 22 provides complete descriptions of the materials, their properties, and the industry standards met for component packaging methods.

Table 3: Component Packaging Materials

<table>
<thead>
<tr>
<th>Element</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>General</td>
<td></td>
</tr>
<tr>
<td>Boxes</td>
<td>Material: Corrugated fiberboard</td>
</tr>
<tr>
<td></td>
<td>Style: RETT w/DF (roll-end tuck-top with dust flaps)</td>
</tr>
<tr>
<td></td>
<td>Color: Natural kraft</td>
</tr>
<tr>
<td></td>
<td>Recyclable: Yes</td>
</tr>
<tr>
<td>Labels</td>
<td>Base material: Matte-coated facestock or synthetic paper</td>
</tr>
<tr>
<td></td>
<td>Adhesive material: Acrylic- or water-based adhesive</td>
</tr>
<tr>
<td></td>
<td>Recyclable: No</td>
</tr>
<tr>
<td>Bags</td>
<td>Moisture-barrier bags²</td>
</tr>
<tr>
<td></td>
<td>Material: Static dissipative polymer/aluminum foil/static dissipative polyethylene</td>
</tr>
<tr>
<td></td>
<td>Standards: Meets the electrical and physical requirements of IPC/JEDEC J-STD-033A, MIL-PRF-81705 Type 1, EIA 583, EIA 541, and EOS/ESD standards</td>
</tr>
<tr>
<td></td>
<td>MVTR (g/100 square in/24 hrs): &lt;0.0003 (FTMS 101 MTH2065)</td>
</tr>
<tr>
<td></td>
<td>Surface resistivity: &lt;10¹² ohms/square (ASTM D-257) or &lt;10¹¹ ohms (ANSI/ESD STM11.11)</td>
</tr>
<tr>
<td></td>
<td>Recyclable: No</td>
</tr>
<tr>
<td>Static-shielding bags³</td>
<td>Material: Static dissipative polyester/metallized shield/static dissipative polyethylene</td>
</tr>
<tr>
<td></td>
<td>Standards: Meets the requirements of MIL-PRF-81705 Type III and EIA 541</td>
</tr>
<tr>
<td></td>
<td>Surface resistivity: &lt;10¹² ohms/square (ASTM D-257)</td>
</tr>
<tr>
<td></td>
<td>Recyclable: No</td>
</tr>
<tr>
<td>Desiccants²</td>
<td>Content material: Montmorillonite (bentonite) clay or molecular sieve</td>
</tr>
<tr>
<td></td>
<td>Packet material: Tyvek, spunbonded olefin</td>
</tr>
<tr>
<td></td>
<td>Recyclable: Individual materials are recyclable, not recyclable as a system</td>
</tr>
<tr>
<td>Humidity indicator cards (HICs)²</td>
<td>Material: Blotting paper impregnated with cobaltous bromide</td>
</tr>
<tr>
<td></td>
<td>Recyclable: Yes</td>
</tr>
<tr>
<td>Tray⁴</td>
<td>Material: Static dissipative polypropylene</td>
</tr>
<tr>
<td></td>
<td>Surface resistivity: &lt;10⁹ to &lt;10¹¹ ohms/square</td>
</tr>
<tr>
<td></td>
<td>Recyclable: Yes</td>
</tr>
<tr>
<td>Trays</td>
<td>For specific information regarding the various trays Micron uses, please contact Micron’s Quality Assurance department</td>
</tr>
</tbody>
</table>
## Table 3: Component Packaging Materials (Continued)

<table>
<thead>
<tr>
<th>Element</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>Internal padding</td>
<td>Expanded polyethylene foam end-cap</td>
</tr>
<tr>
<td></td>
<td>Material: Low-density polyethylene</td>
</tr>
<tr>
<td></td>
<td>Surface resistivity: $10^9$ to $10^{11}$ ohms/square</td>
</tr>
<tr>
<td></td>
<td>Recyclable: Yes</td>
</tr>
<tr>
<td></td>
<td>Or Padpak</td>
</tr>
<tr>
<td></td>
<td>Material: Kraft paper</td>
</tr>
<tr>
<td></td>
<td>Recyclable: Yes</td>
</tr>
<tr>
<td>Tape-and-reel</td>
<td></td>
</tr>
<tr>
<td>Take-up reels</td>
<td>Color: White or black</td>
</tr>
<tr>
<td></td>
<td>Material: High-impact polystyrene, topically coated with antistatic material</td>
</tr>
<tr>
<td></td>
<td>Surface resistivity: $&lt;10^{11}$ ohms/square (both sides) per ASTM D-257</td>
</tr>
<tr>
<td></td>
<td>Recyclable: Yes</td>
</tr>
<tr>
<td>Carrier tape</td>
<td>Material: Polystyrene with carbon</td>
</tr>
<tr>
<td></td>
<td>Surface resistivity: $&lt;10^{12}$ $\geq 10^5$ ohms/square (both sides) per ASTM D-257, static dissipative per EIA 541</td>
</tr>
<tr>
<td></td>
<td>Recyclable: Yes</td>
</tr>
<tr>
<td>Cover tape</td>
<td>Material: Antistatic polyester film/antistatic adhesive coating</td>
</tr>
<tr>
<td></td>
<td>Surface resistivity: $&lt;10^{12}$ $\geq 10^5$ ohms/square (both sides) per ASTM D-257, static dissipative per EIA 541</td>
</tr>
<tr>
<td></td>
<td>Recyclable: No</td>
</tr>
</tbody>
</table>

Notes:  
1. Contact the factory for questions regarding omitted information.  
2. Provided with MST Level 2 through 5A products shipped in trays and tape-and-reels only.  
3. Provided with MST Level 1 product only.  
4. Applicable to product shipped in trays only.  
5. Applicable to product shipped in tape-and-reel only.
Revision History

Rev. Z .......................................................... 10/2020
• Updated Figure 1

Rev. Y .......................................................... 8/2020
• Updated SSD packaging figures
• Updated doc ID number

Rev. X .......................................................... 4/19
• Added SD, microSD and M.2 flat packaging figures
• Added pin 1 information to Pin 1 Direction on Trays and Location of Pin 1 in Tape-and-Reel Packaging figures

Rev. W .......................................................... 10/18
• Updated Air Allowance in Moisture-Barrier and Static-Shielding Bags section

Rev. V .......................................................... 3/18
• Updated desiccant composition

Rev. U .......................................................... 1/18
• Updated M.2 SSD packaging figure

Rev. T .......................................................... 9/17
• Updated eUSB packaging figure

Rev. S .......................................................... 6/17
• Added CSN-04 note to page 1

Rev. R .......................................................... 5/17
• Added eUSB Packaging Figure

Rev. Q .......................................................... 3/17
• Updated Figure 7: 2.5-Inch SSD Packaging to remove antistatic bag from tray
• Removed “SSD card” text from Figures 6–8 and “M.2 card” text from Figure 9

Rev. P .......................................................... 12/15
• Updated text under Figures 1 and 3 to include 1 in the number of packages that may be placed in a master shipping container
• Added ESD Tape Example figure (Figure 2)
• Updated Figures 1, 3, 4, 6 and 8 to include box orientation (opening and non-opening sides) and ESD tape
• Replaced 2.5-Inch SSD Packaging figure (Figure 7)

Rev. O .......................................................... 11/14
• Updated Tray Packaging, Tape-and-Reel Packaging, and Reel figures
• Deleted Microdisplay information

Rev. N .......................................................... 1/13
• Updated mSATA information
• Added M.2 information
• Added thermoformed packaging information

Rev. M .......................................................... 6/12
• Added micropyline panel information

Rev. L .......................................................... 2/12
• Added mSATA information

Rev. K .......................................................... 2/12
• Updated EIA specification information
Revision History

Rev. J ................................. 8/11
  • Added security tape information

Rev. I ................................. 3/10
  • Updated template
  • Added component packaging information from former CSNs -15, -17, and -21
  • Changed cobaltous chloride... to cobaltous bromide... in Table 3

Rev. H ................................. 8/07
  • Added customer revision to Figure 3 on page 3

Rev. G ................................. 3/07
  • Added new Humidity Indicator Card information to text and to Figures 5–9 on pages 6–8

Rev. F ................................. 3/06
  • Added Figure 1 on page 2 and Figure 14 on page 11

Rev. E ................................. 6/05
  • Updated Figure 4 on page 4

Rev. D ................................. 5/05
  • Added Pb-free information

Rev. C ................................. 2/05

Rev. B ................................. 3/04

Rev. A ................................. 2/04
  • Initial release